



Bill of Materials

TI DESIGNS

TIPD205: $\pm 100\text{A}$ Bus Bar Current Sensor using Open-Loop Fluxgate Sensors Design Guide

Item #	Quantity	Value	Designator	Description	Manufacturer	PartNumber	Supplier Part Number 1
1	1		PCB	Printed Circuit Board	Any	TIPD-205	
2	1	10	R3	RES, 10ohm, 0.1%, 1/5W, 0805	Vishay Thin Film	PATT0805E10R0BGT1	764-1050-2-ND
3	1	OPA320AID	U3	IC, Precision, 20MHz, 0.9pA, Low-Noise, RRIO, CMOS Op-Amp	TI	OPA320AIDBVR	
4	1	PEC03DAAN	J1	Header, Male 2x3-pin, 100mil spacing	Sullins	PEC03DAAN	S2012E-03-ND
5	2		U1, U2	Fluxgate Magnetic Field Sensor, RTJ0020G	Texas Instruments	DRV425RTJR	
6	2	10k	R4, R5	RES, 10kohm, 1%, 1/16W, 0402, RES, 10kohm, 1%, 1/16W	ROHM SEMICONDUCTOR	MCR01MRTF1002	RHM10.0KCDCT-ND
7	2	5.1	R1, R2	RES, 5.1ohm, 1%, 1/8W, 0805, RES, 5.1ohm, 1%, 1/8W	Panasonic	ERJ6RQF5R1V	ERJ-6RQF5R1V-ND
8	5	1u	C1, C2, C3, C4, C5	CAP, CERM, 1uF, 25V, X7R, 10%, 0603	TDK	C1608X7R1E105K080AB	445-5956-1-ND

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